

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/07/2022

Details for "SN74LVCH16373ADL"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
SN74LVCH16373ADL	NIPDAU	Level-1-260C-UNLIM	TI MALAYSIA A/T	DL 48	7.49x15.88x2.59	659.7

*Total Device Mass
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Iron	7439-89-6	0.000001	0.000149	1	0	0
Other Nonferrous Metals and Alloys	Beryllium	7440-41-7	0.000001	0.000149	1	0	0
Other Nonferrous Metals and Alloys	Calcium	7440-70-2	0.000002	0.000299	3	0	0
Other Nonferrous Metals and Alloys	Yttrium	7440-65-5	0.000005	0.000746	7	0.000001	0
Precious Metals	Gold	7440-57-5	0.669999	99.997612	999976	0.101562	1016
Precious Metals	Silver	7440-22-4	0.000007	0.001045	10	0.000001	0
Sub-Total			0.670015	100	1000000	0.101564	1016
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.623689	80.000026	800000	0.094542	945
Thermoplastics	Epoxy	85954-11-6	0.155922	19.999974	200000	0.023635	236
Sub-Total			0.779611	100	1000000	0.118177	1182
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	109.23291	97.425	974250	16.558054	165581
Copper and Its Alloys	Iron	7439-89-6	2.69088	2.4	24000	0.407897	4079
Copper and Its Alloys	Phosphorus	7723-14-0	0.016818	0.015	150	0.002549	25
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.033636	0.03	300	0.005099	51
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.033636	0.03	300	0.005099	51
Zinc and Its Alloys	Zinc	7440-66-6	0.11212	0.1	1000	0.016996	170
Sub-Total			112.12	100	1000000	16.995693	169957
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	1.65168	90	900000	0.25037	2504
Precious Metals	Gold	7440-57-5	0.04588	2.5	25000	0.006955	70
Precious Metals	Palladium	7440-05-3	0.13764	7.5	75000	0.020864	209
Sub-Total			1.8352	100	1000000	0.278189	2782
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	476.731341	88	880000	72.265248	722652
Other Plastics and Rubber	Carbon Black	1333-86-4	1.62522	0.3	3000	0.246359	2464
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	2.979571	0.55	5500	0.451658	4517
Thermoplastics	Epoxy	85954-11-6	60.404028	11.15	111500	9.156335	91563
Sub-Total			541.74016	100	1000000	82.1196	821196
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	2.551557	100	1000000	0.386777	3868
Sub-Total			2.551557	100	1000000	0.386777	3868
Total			659.696543			100	1000000

Important Note
 The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSiS or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights. See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.